JSCJ

MSDS Report

Report NO.: M000004000041

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC50SN03
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition		CAS No.	% of weight	% of weight total
Wafer	Silicon		7440-21-3	100.0000%	4.63%
Lead Frame	Copper		7440-50-8	97.5200%	34.28%
	Iron		7439-89-6	2.3500%	
	P		7723-14-0	0.0800%	
	Plating Ag		7440-22-4	0.0500%	
Solder	Lead		7439-92-1	85.0000%	3.66%
	Tin		7440-31-5	4.3500%	
	Silver		7440-22-4	2.1500%	
	Butanediol mixture		107-88-0	7.5000%	
	Modified castor oil		61788-85-0	1.0000%	
Wire	Ribbon		7429-90-5	100.0000%	2.43%
	AuPdCu	Copper	7440-50-8	97.9500%	
		Palladium	7440/5/3	1.8000%	
		Gold	7440-57-5	0.2500%	
Mold Compound	Silica		60676-86-0	82.0000%	52.59%
	Epoxy Resin		85954-11-6	10.0000%	
	Phenol Resin		26834-02-6	7.5000%	
	Carbon black		1333-86-4	0.5000%	
Plating	Tin		7440-31-5	99.9900%	2.41%
	Other		/	0.0100%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.